

Amendments to the Specification:

Please replace paragraph [0020] with the following amended paragraph [0020]:

[0020] As illustrated in Fig. 2, a thin .125" thick copper spreader 50 is soldered to the 90% graphite foam core 30 of the graphite foam heat sink assembly 25. However, it is possible to have a copper spreader of a different thickness based on the application. The thermal resistance between the copper and graphite is kept minimum by soldering the two surfaces using solder either 50/50 (Sn/Pb) or 63/37 (Sn/Pb). The copper spreader 50 makes contact with [[the]] a heat spreader of an electronic component 51. The copper spreader's 50 mechanical tolerances on the flatness and surface finish can be held much tighter than that of machined graphite. Since the flatness and surface finish are critical in the area of contact to the spreader on the electronic component 51, an optimum copper spreader 50, C10100, is illustrated, however, various copper spreaders can be used. Moreover, copper has a high thermal conductivity (350 Watts/M*k) and does not add much to the overall weight because the thickness is kept to its minimum of .125".